



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

TZ-CHENG CHIU

Serial No. 10/631,130 (TI-35061)

Filed July 31, 2003

For: COMPOSITE LID FOR LAND GRIP ARRAY
(LGA) FLIP CHIP PACKAGE ASSEMBLY

Art Unit 2825

Examiner Calvin Lee

Customer No. 23494

Director of the United States
Patent and Trademark Office
P. O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING OR TRANSMISSION UNDER 37 CFR 1.8

I hereby certify that the attached document is being deposited with the United States Postal Service with sufficient postage for First Class Mail in an envelope addressed to Director of the United States Patent and Trademark Office, P.O. Box 1450,, Alexandria, VA 22313-1450 or is being facsimile transmitted on the date indicated below:

3-26-04

Jay M. Cantor, Reg. No. 19,906

ELECTION

Sir:

Responsive to the Office action dated march 15, 2004, applicant elects the invention listed as (1) and including claims 1 to 10 without traverse.

Claims 11 to 24 are retained pending filing of a divisional application therefore.

Action and allowance are respectfully requested.

Respectfully submitted,

Jay M. Cantor

Attorney for Applicant(s)

Reg. No. 19,906

Texas Instruments Incorporated
P. O. Box 655474, MS 3999
Dallas, Texas 75265
(301) 424-0355 (Phone)
(972) 917-5293 (Phone)
(301) 279-0038 (Fax)